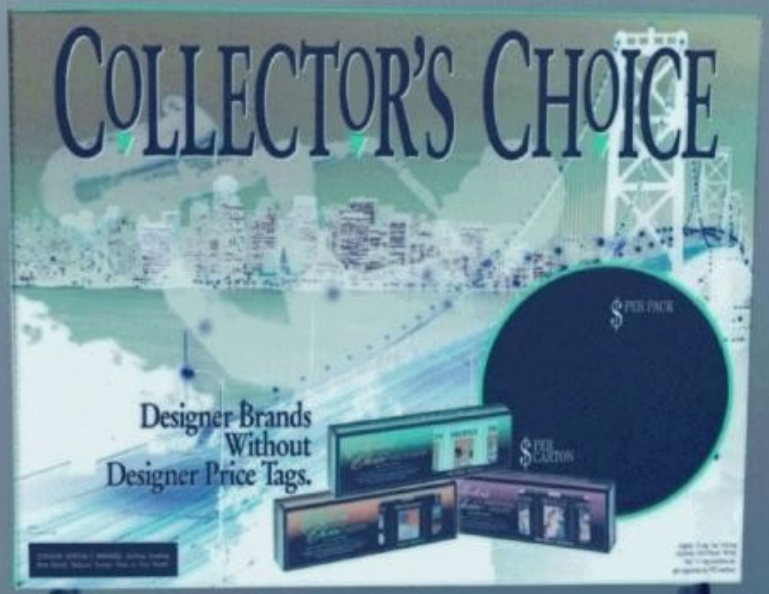

Source: https://www.industrydocuments.ucsf.edu/docs/hspn0003
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